

## General Description

The WST3426 is the highest performance trench N-Ch MOSFET with extreme high cell density, which provide excellent R<sub>DS(on)</sub> and gate charge for most of the small power switching and load switch applications.

The WST3426 meet the RoHS and Green Product requirement with full function reliability approved.

## Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent C<sub>dv/dt</sub> effect decline
- Green Device Available

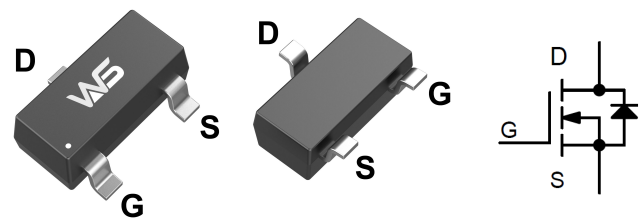
## Product Summary

| BVDSS | R <sub>DS(on)</sub> | I <sub>D</sub> |
|-------|---------------------|----------------|
| 20V   | 60mΩ                | 3.0A           |

## Applications

- High Frequency Point-of-Load Synchronous Small power switching for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

## SOT-23 Pin Configuration



## Absolute Maximum Ratings

| Symbol                               | Parameter   | Rating     | Units |
|--------------------------------------|---|------------|-------|
| V <sub>DS</sub>                      | Drain-Source Voltage  | 20         | V     |
| V <sub>GS</sub>                      | Gate-Source Voltage   | ±12        | V     |
| I <sub>D</sub> @T <sub>C</sub> =25°C | Continuous Drain Current, V <sub>GS</sub> @ 4.5V <sup>1</sup> | 3.0        | A     |
| I <sub>D</sub> @T <sub>C</sub> =70°C | Continuous Drain Current, V <sub>GS</sub> @ 4.5V <sup>1</sup> | 2.5        | A     |
| I <sub>DM</sub>                      | Pulsed Drain Current <sup>2</sup>                             | 10         | A     |
| P <sub>D</sub> @T <sub>A</sub> =25°C | Total Power Dissipation <sup>3</sup>                          | 1.0        | W     |
| T <sub>STG</sub>                     | Storage Temperature Range                                     | -55 to 150 | °C    |
| T <sub>J</sub>                       | Operating Junction Temperature Range                          | -55 to 150 | °C    |

## Thermal Data

| Symbol           | Parameter  | Typ. | Max. | Unit |
|------------------|--|------|------|------|
| R <sub>θJA</sub> | Thermal Resistance Junction-ambient <sup>1</sup> | ---  | 200  | °C/W |
| R <sub>θJC</sub> | Thermal Resistance Junction-Case <sup>1</sup>    | ---  | 75   | °C/W |

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

| Symbol                       | Parameter                                      | Conditions   | Min. | Typ.  | Max.      | Unit                       |
|------------------------------|--|--|------|-------|-----------|----------------------------|
| $BV_{DSS}$                   | Drain-Source Breakdown Voltage                 | $V_{GS}=0V, I_D=250\mu A$                            | 20   | ---   | ---       | V                          |
| $\Delta BV_{DSS}/\Delta T_J$ | BVDSS Temperature Coefficient                  | Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$   | ---  | 0.024 | ---       | $V/^\circ\text{C}$         |
| $R_{DS(ON)}$                 | Static Drain-Source On-Resistance <sup>2</sup> | $V_{GS}=4.5V, I_D=1.8A$                              | ---  | 60    | 75        | m $\Omega$                 |
|                              |  | $V_{GS}=2.5V, I_D=1.5A$                              | ---  | 70    | 85        |                            |
|                              |  | $V_{GS}=1.8V, I_D=1A$                                |      | 90    | 110       |                            |
| $V_{GS(th)}$                 | Gate Threshold Voltage                         | $V_{GS}=V_{DS}, I_D=250\mu A$                        | 0.3  | 0.85  | 1.2       | V                          |
| $\Delta V_{GS(th)}$          | $V_{GS(th)}$ Temperature Coefficient           |  | ---  | -2.51 | ---       | $\text{mV}/^\circ\text{C}$ |
| $I_{DSS}$                    | Drain-Source Leakage Current                   | $V_{DS}=16V, V_{GS}=0V, T_J=25^\circ\text{C}$        | ---  | ---   | 1         | $\mu\text{A}$              |
|                              |  | $V_{DS}=16V, V_{GS}=0V, T_J=55^\circ\text{C}$        | ---  | ---   | 5         |                            |
| $I_{GSS}$                    | Gate-Source Leakage Current                    | $V_{GS}=\pm 8V, V_{DS}=0V$                           | ---  | ---   | $\pm 100$ | nA                         |
| $g_{fs}$                     | Forward Transconductance                       | $V_{DS}=5V, I_D=3A$                                  | ---  | 8.0   | ---       | S                          |
| $R_g$                        | Gate Resistance                                | $V_{DS}=0V, V_{GS}=0V, f=1\text{MHz}$                | ---  | 1.5   | 3.0       | $\Omega$                   |
| $Q_g$                        | Total Gate Charge (4.5V)                       | $V_{DS}=15V, V_{GS}=4.5V, I_D=1A$                    | ---  | 5.4   | ---       | nC                         |
| $Q_{gs}$                     | Gate-Source Charge                             |  | ---  | 0.44  | ---       |                            |
| $Q_{gd}$                     | Gate-Drain Charge                              |  | ---  | 1.0   | ---       |                            |
| $T_{d(on)}$                  | Turn-On Delay Time                             | $V_{DD}=10V, V_{GS}=4.5V, R_G=3.3\Omega$<br>$I_D=1A$ | ---  | 1.5   | ---       | ns                         |
| $T_r$                        | Rise Time                                      |  | ---  | 25.6  | ---       |                            |
| $T_{d(off)}$                 | Turn-Off Delay Time                            |  | ---  | 16.8  | ---       |                            |
| $T_f$                        | Fall Time                                      |  | ---  | 5.5   | ---       |                            |
| $C_{iss}$                    | Input Capacitance                              | $V_{DS}=15V, V_{GS}=0V, f=1\text{MHz}$               | ---  | 320   | ---       | pF                         |
| $C_{oss}$                    | Output Capacitance                             |  | ---  | 35    | ---       |                            |
| $C_{riss}$                   | Reverse Transfer Capacitance                   |  | ---  | 22    | ---       |                            |

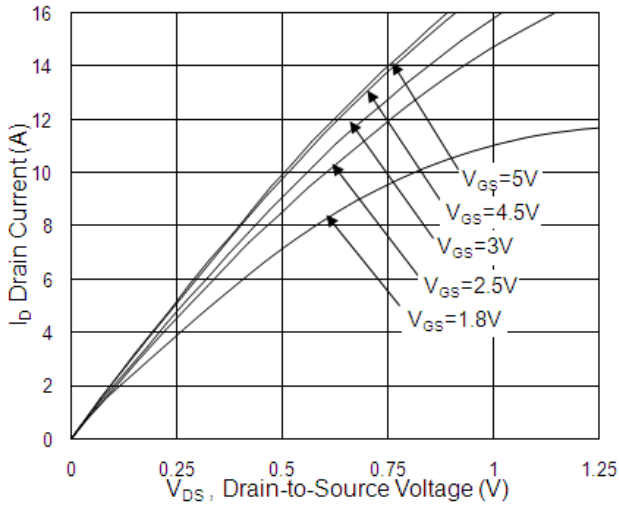
**Diode Characteristics**

| Symbol   | Parameter                                | Conditions                                       | Min. | Typ. | Max. | Unit |
|----------|--|--|------|------|------|------|
| $I_S$    | Continuous Source Current <sup>1,4</sup> | $V_G=V_D=0V$ , Force Current                     | ---  | ---  | 3.0  | A    |
| $I_{SM}$ | Pulsed Source Current <sup>2,4</sup>     |  | ---  | ---  | 9.0  | A    |
| $V_{SD}$ | Diode Forward Voltage <sup>2</sup>       | $V_{GS}=0V, I_S=1A, T_J=25^\circ\text{C}$        | ---  | ---  | 1.2  | V    |
| $t_{rr}$ | Reverse Recovery Time                    | $I_F=2A, di/dt=100A/\mu s, T_J=25^\circ\text{C}$ | ---  | 5.1  | ---  | nS   |
| $Q_{rr}$ | Reverse Recovery Charge                  |  | ---  | 1.5  | ---  | nC   |

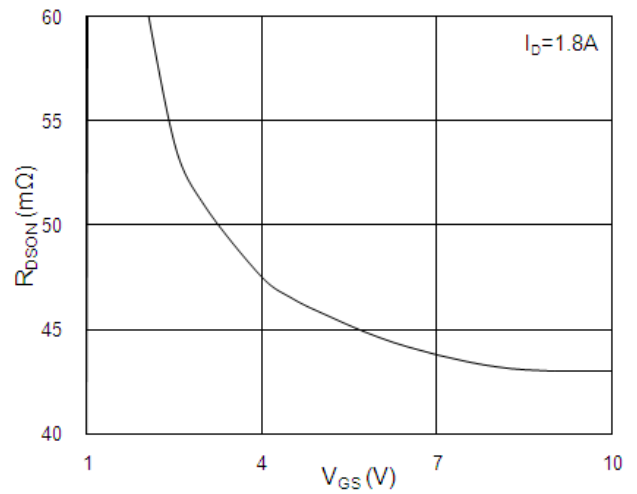
Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper,  $t < 10\text{sec}$ .
- 2.The data tested by pulsed, pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$
- 3.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 4.The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.

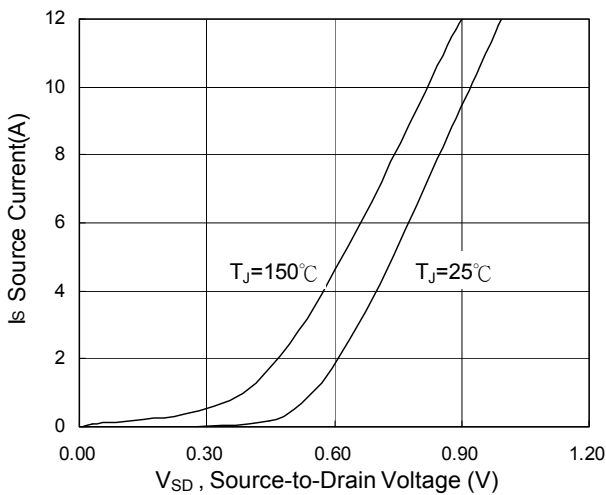
**Typical Characteristics**



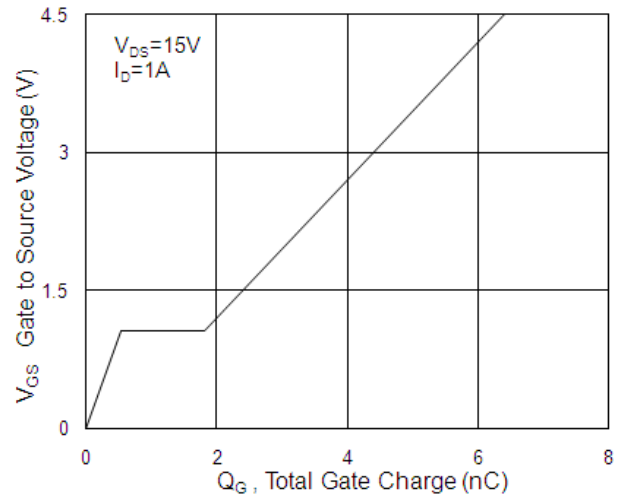
**Fig.1 Typical Output Characteristics**



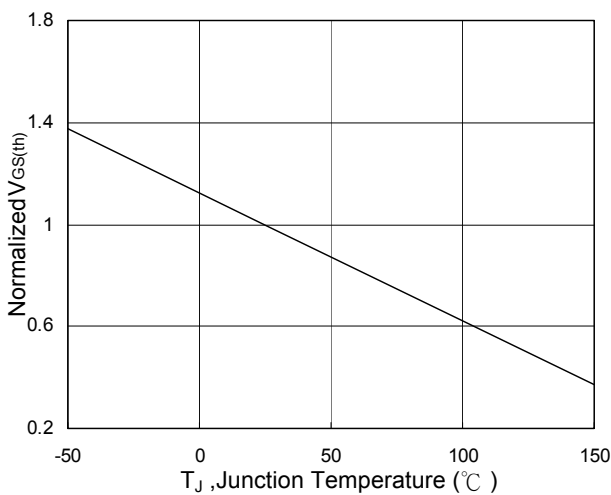
**Fig.2 On-Resistance vs. Gate-Source**



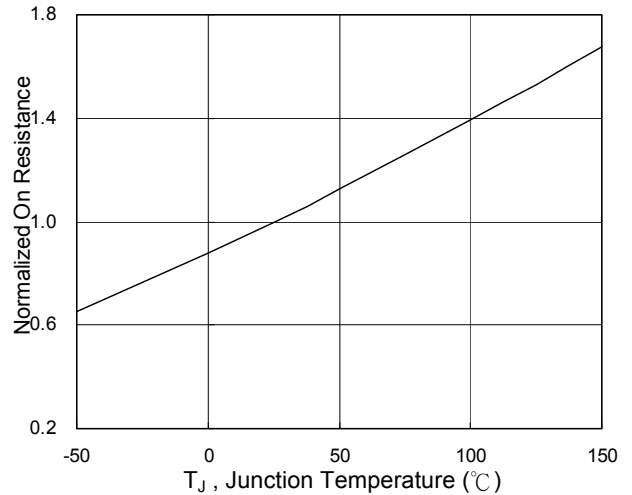
**Fig.3 Forward Characteristics Of Reverse**



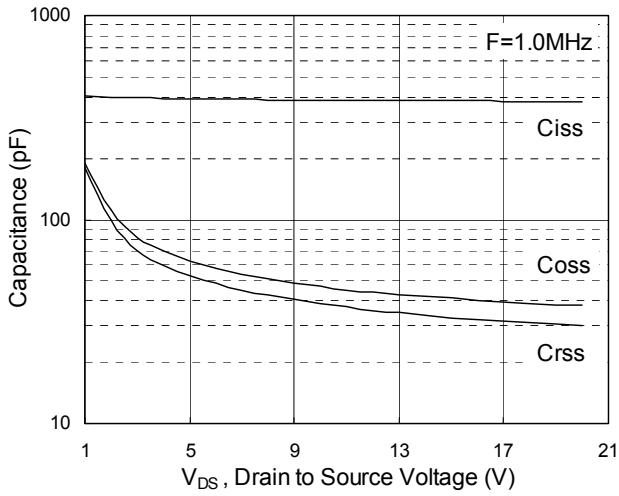
**Fig.4 Gate-Charge Characteristics**



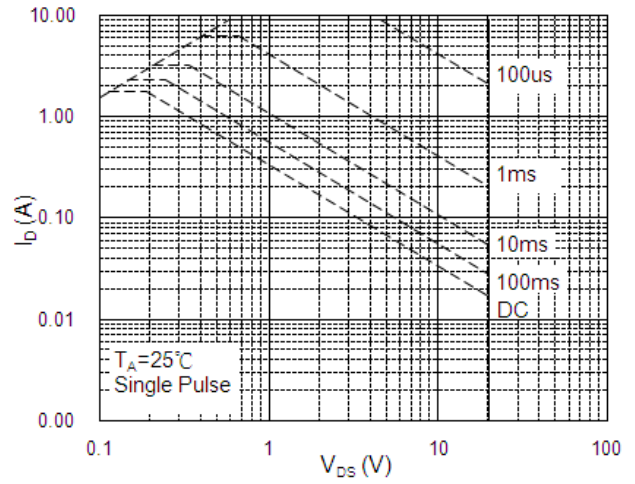
**Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$**



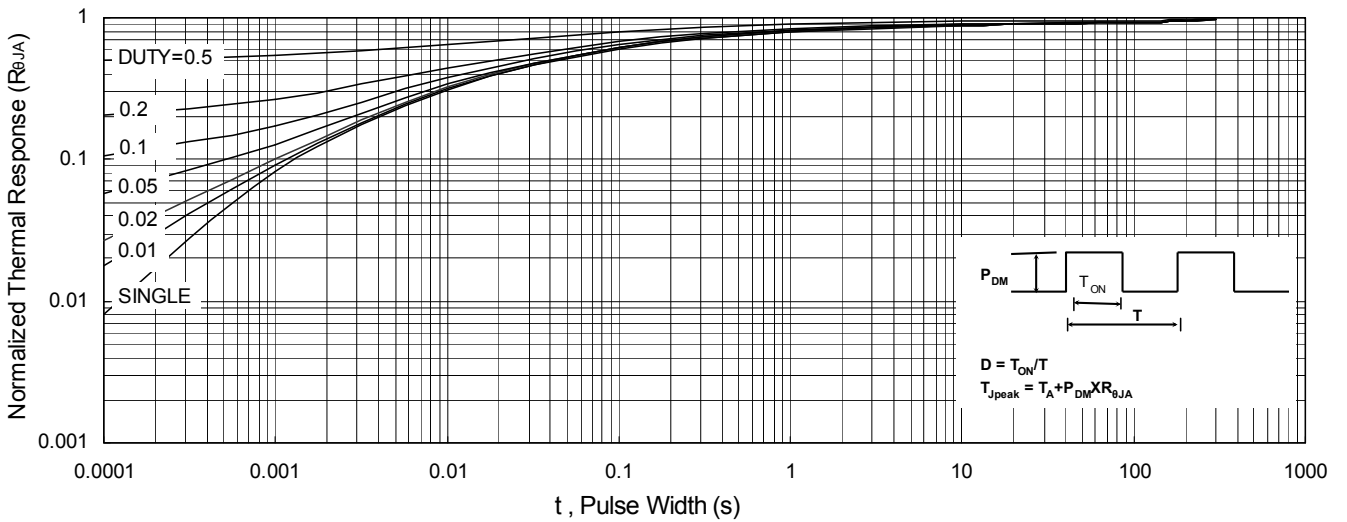
**Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$**



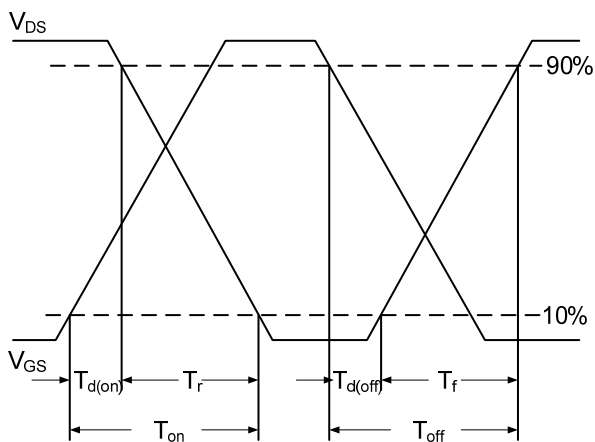
**Fig.7 Capacitance**



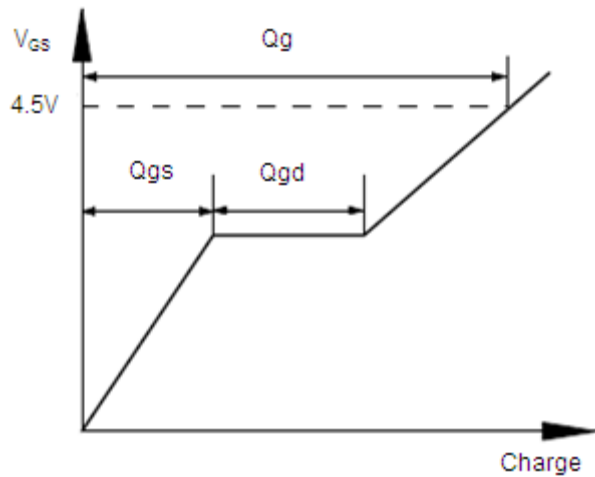
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**



**Fig.10 Switching Time Waveform**



**Fig.11 Gate Charge Waveform**



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